



## 100V N-Channel MOSFETs

### General Description

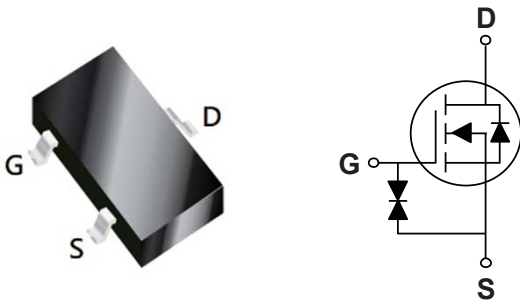
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

$BV_{DSS}$	$R_{DS(ON)}$	$I_D$
100 V	5.5 $\Omega$	300 mA

### Features

- $R_{DS(ON)} \leq 5.5\Omega @ V_{GS}=10V$
- Improved dv/dt Capability
- Fast Switching
- Green Device Available
- G-S ESD Protection Diode Embedded
- ESD protected up to 2KV

SOT-23 Pin Configuration



### Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-Held Instruments

### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current - Continuous ( $T_A=25^\circ\text{C}$ )	300	mA
$I_{DM}$	Drain Current - Pulsed (NOTE 1)	1.2	A
$P_D$	Power Dissipation ( $T_A=25^\circ\text{C}$ )	1.56	W
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
Marking Code		a	

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	80	$^\circ\text{C/W}$



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Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	100	---	---	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V	---	---	1	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±20	uA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =0.15A	---	---	5.5	Ω
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.12A	---	---	6.5	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.5	---	3.0	V

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
C <sub>ISS</sub>	Input Capacitance	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V, f=1MHz	---	60	---	pF
C <sub>OSS</sub>	Output Capacitance		---	18	---	
C <sub>rSS</sub>	Reverse Transfer Capacitance		---	5.2	---	

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	0.3	A
I <sub>SM</sub>	Pulsed Source Current		---	---	0.6	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =0.2A	---	---	1	V
T <sub>rr</sub>	Reverse Recovery Time	V <sub>R</sub> =100V, I <sub>S</sub> =0.1A, di/dt=100A/us	---	8.5	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	5.8	---	nC

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



### Characteristics Curves

FIG. 1- $I_D$  vs  $T_C$

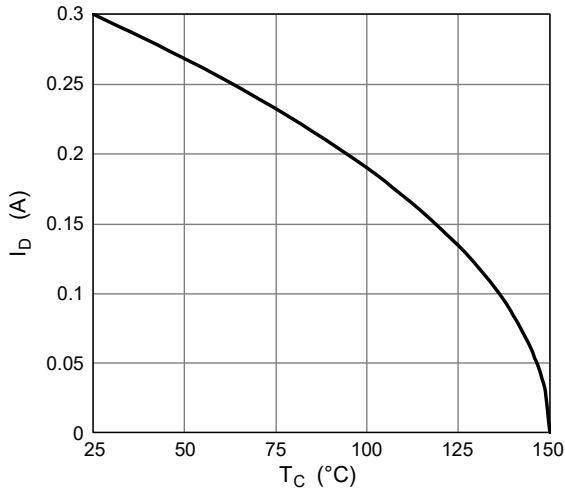


FIG. 2-Normalized  $R_{DS(ON)}$  vs  $T_J$

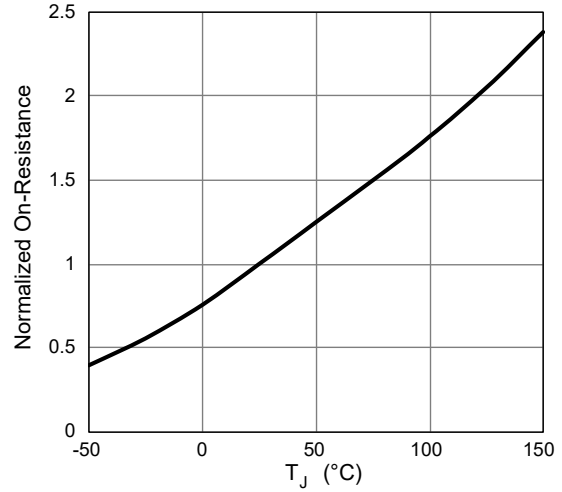


FIG. 3-Normalized  $V_{th}$  vs  $T_J$

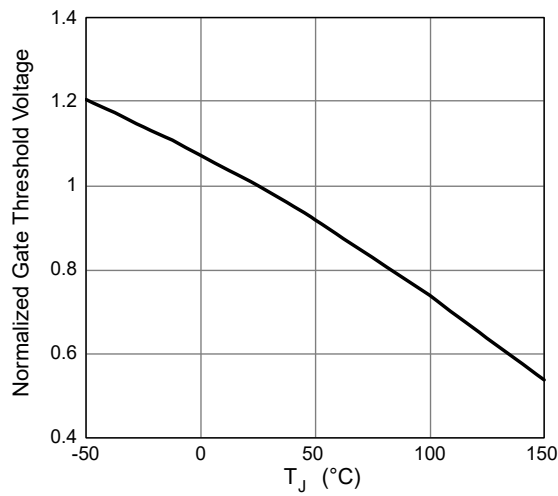


FIG. 4- $R_{DS(ON)}$  vs  $I_D$

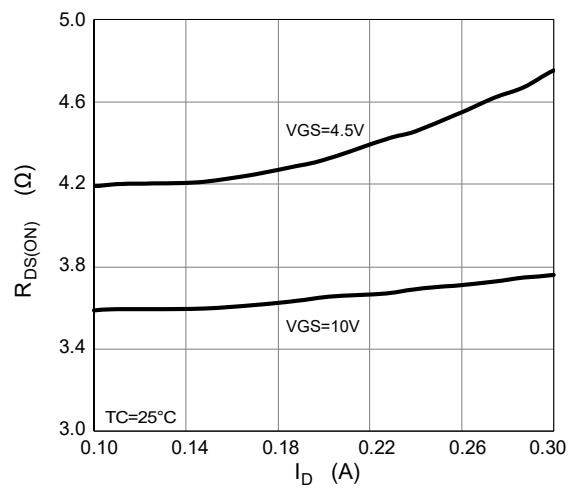


FIG. 5-Normalized Transient Impedance

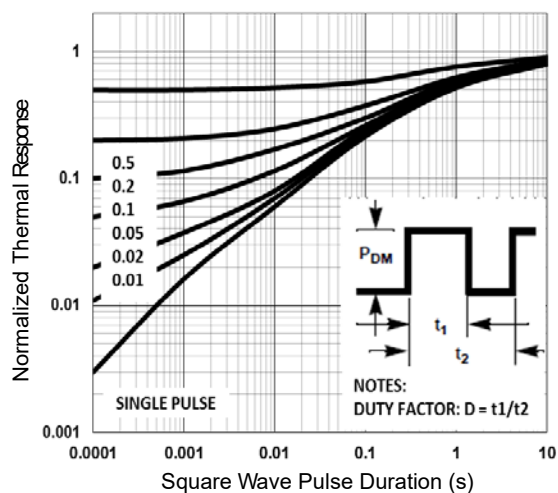
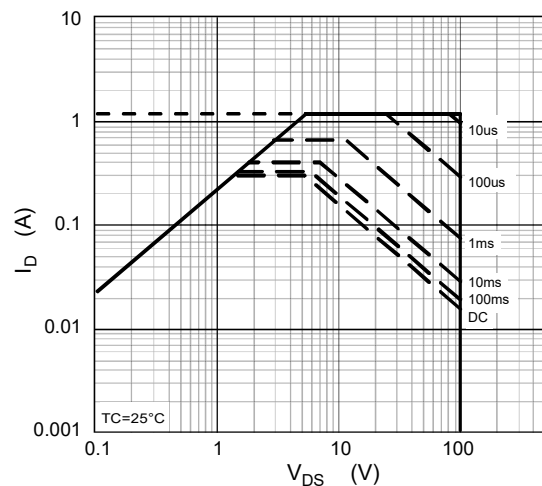


FIG. 6-Maximum Safe Operation Area



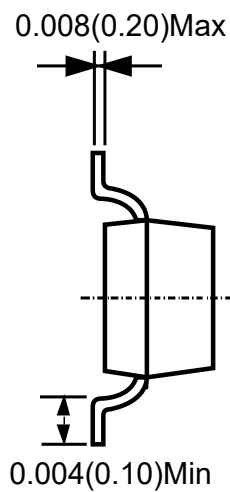
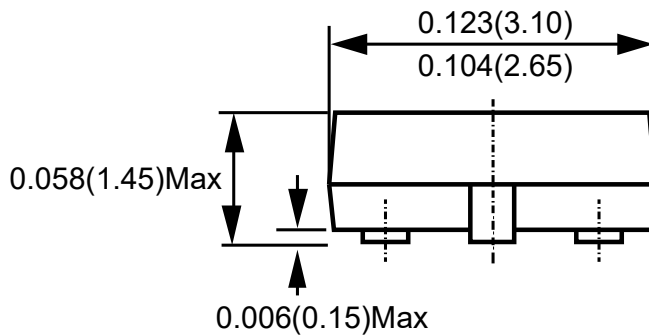
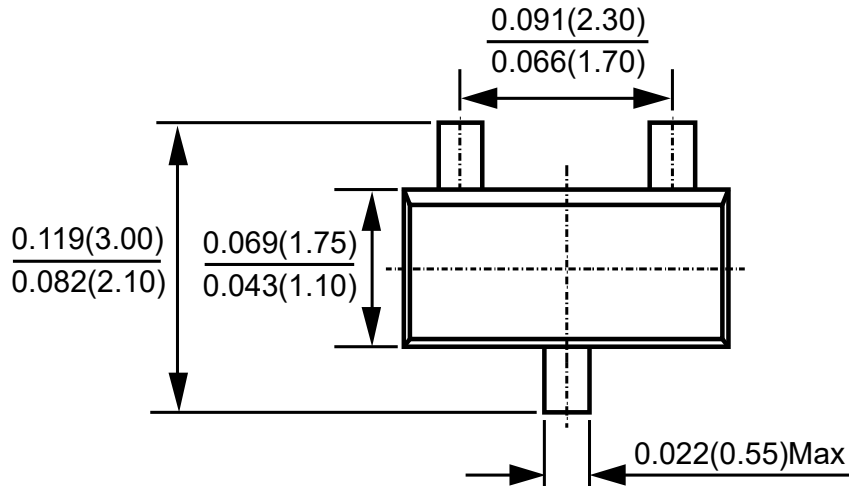


TNMNM55H



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## Package Outline Dimensions



**SOT-23**

Dimensions in inches and (millimeters)



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